US00D897974S

(12) **United States Design Patent** (10) **Patent No.: US D897,974 S**
Taguchi et al. (45) **Date of Patent: ** Oct. 6, 2020**

(54) **SEMICONDUCTOR WAFER**

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(72) Inventors: **Tomoya Taguchi**, Hamamatsu (JP); **Takeshi Sakamoto**, Shizuoka (JP)

(73) Assignee: **HAMAMATSU PHOTONICS K.K.**, Hamamatsu-shi, Shizuoka (JP)

(**) Term: **15 Years**

(21) Appl. No.: **35/506,381**

(22) Filed: **Sep. 5, 2018**

(80) **Hague Agreement Data**

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Int. Reg. Date:	**Sep. 5, 2018**
Int. Reg. Pub. Date:	**Mar. 8, 2019**

(30) **Foreign Application Priority Data**

Mar. 29, 2018	(JP)	2018-006854
Mar. 29, 2018	(JP)	2018-006855

(51) **LOC (12) Cl.** **13-03**
(52) **U.S. Cl.**
USPC **D13/182**
(58) **Field of Classification Search**
USPC D13/182, 102; D24/225
(Continued)

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(Continued)

Primary Examiner — Rhea Shields
(74) *Attorney, Agent, or Firm* — Faegre Drinker Biddle & Reath LLP

(57) **CLAIM**

The ornamental design for a semiconductor wafer, as shown and described.

DESCRIPTION

1.-2. Semiconductor wafer
1.1 : Front view
1.2 : Rear view
1.3 : Top plan view
1.4 : Bottom view
1.5 : Right side view
1.6 : Left side view
1.7 : Enlarged view showing a portion of Reproduction **1.2** defined by lines **1.7**-**1.7** and **1.7'**-**1.7'**
1.8 : Enlarged view showing a portion of Reproduction **1.7** defined by lines **1.8**-**1.8** and **1.8'**-**1.8'**
1.9 : Enlarged view showing a portion of Reproduction **1.7** defined by lines **1.9**-**1.9** and **1.9'**-**1.9'**
1.10 : Enlarged view showing a portion of Reproduction **1.7** defined by lines **1.10**-**1.10** and **1.10'**-**1.10'**
1.11 : Enlarged cross-sectional view along line **1.11** of Reproduction **1.8**
1.12 : Enlarged cross-sectional view along line **1.12** of Reproduction **1.9**
1.13 : Enlarged cross-sectional view along line **1.13** of Reproduction **1.10**
2.1 : Front view
2.2 : Rear view
2.3 : Top plan view
2.4 : Bottom view
2.5 : Right side view
2.6 : Left side view

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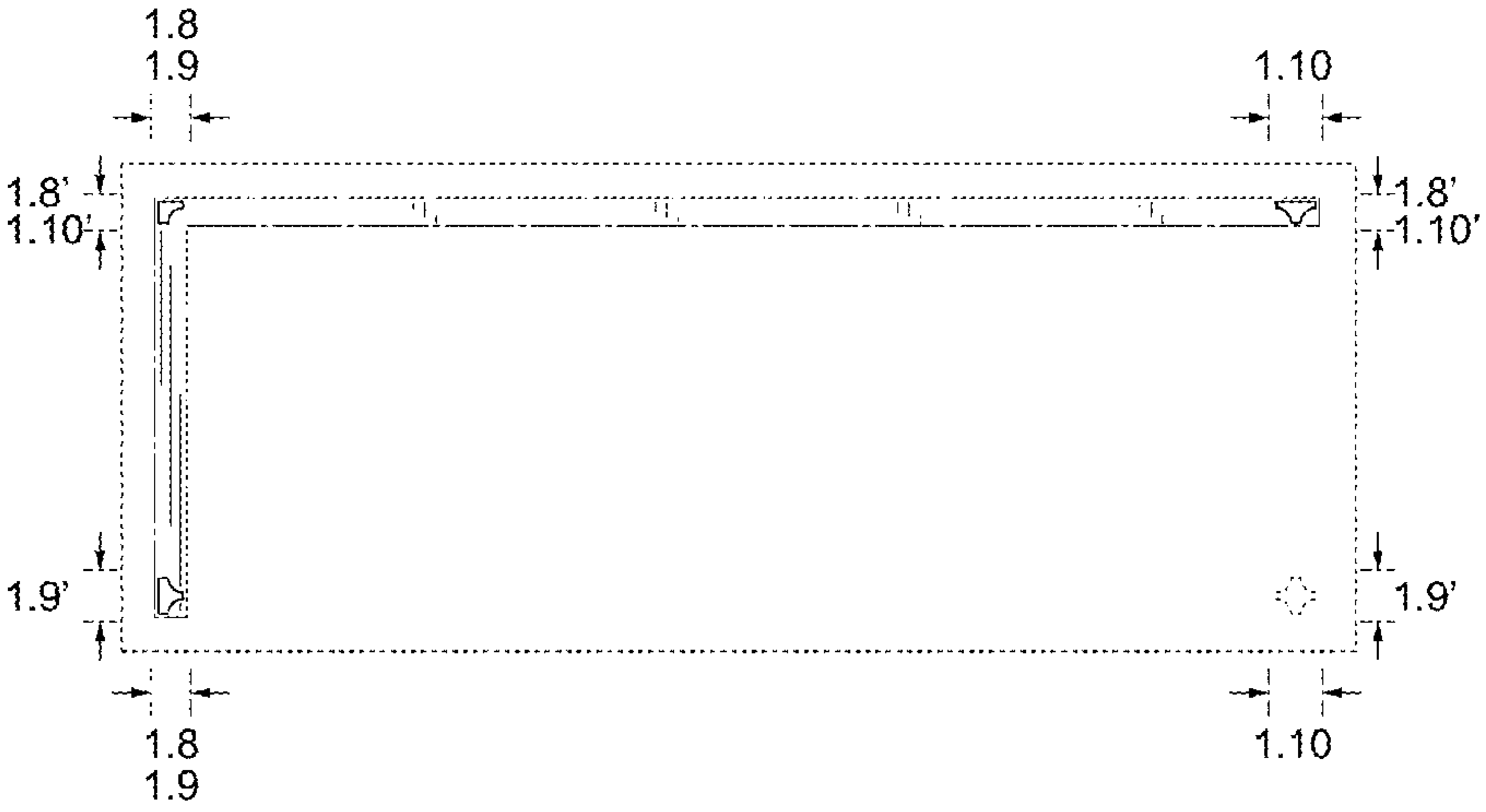

2.7 : Enlarged view showing a portion of Reproduction **2.2** defined by lines **2.7**-**2.7** and **2.7'**-**2.7'**

2.8 : Enlarged view showing a portion of Reproduction **2.7** defined by lines **2.8**-**2.8** and **2.8'**-**2.8'**

2.9 : Enlarged view showing a portion of Reproduction **2.7** defined by lines **2.9**-**2.9** and **2.9'**-**2.9'**

2.10 : Enlarged view showing a portion of Reproduction **2.7** defined by lines **2.10**-**2.10** and **2.10'**-**2.10'**

2.11: Enlarged cross-sectional view along line **2.11** of Reproduction **2.8**

2.12 : Enlarged cross-sectional view along line **2.12** of Reproduction **2.9**

2.13 : Enlarged cross-sectional view along line **2.13** of Reproduction **2.10**

1.-2. Designs 1 and 2: each article is a wafer used in the production of photodetectors, or the like; the parts shown in solid lines are parts for which design registration is sought; design 1: reproduction **1.7** is an enlarged view of upper left part of reproduction **1.2**; reproduction **1.8** is an enlarged view of upper left part of reproduction **1.7**; reproduction **1.9** is an enlarged view of bottom left part of reproduction **1.7**; reproduction **1.10** is an enlarged view of upper right part of reproduction **1.7**; reproduction **1.11** is an enlarged cross-sectional view in the vertical direction of reproduction **1.8**; reproduction **1.12** is an enlarged cross-sectional view in the vertical direction of reproduction **1.9**; reproduction **1.13** is an enlarged cross-sectional view in the horizontal direction of reproduction **1.10**; design 2: reproduction **2.7** is an enlarged view of upper left part of reproduction **2.2**; reproduction of **2.8** is an enlarged view of upper left part of reproduction **2.7**; reproduction **2.9** is an enlarged view of bottom left part of reproduction **2.7**; reproduction **2.10** is an enlarged view of upper right part of reproduction **2.7**; reproduction **2.11** is an enlarged cross-sectional view in the vertical direction of reproduction **2.8**; reproduction **2.12** is an enlarged cross-sectional view in the vertical direction of reproduction **2.9**; reproduction **2.13** is an enlarged cross-sectional view in the horizontal direction of reproduction **2.10**. In the drawings, the dash-dot-dash broken lines are for the purpose of illustrating the boundaries of the claimed design and form no part of the claimed design. The evenly spaced broken lines are for the purpose of showing portions of the semiconductor wafer and form no part of the claimed design.

1 Claim, 26 Drawing Sheets

(58) **Field of Classification Search**
CPC B23K 26/0736
See application file for complete search history.

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D733,911	S	*	7/2015	Ito	D24/225
D733,912	S	*	7/2015	Ito	D24/225
D733,913	S	*	7/2015	Ito	D24/225
D739,954	S	*	9/2015	Ito	D24/225
D740,439	S	*	10/2015	Ito	D24/225
D740,440	S	*	10/2015	Ito	D24/225
D750,799	S	*	3/2016	Ito	D24/225
D750,800	S	*	3/2016	Ito	D24/225
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D785,576	S	*	5/2017	Motoyama	D13/182
D786,810	S	*	5/2017	Motoyama	D13/182
D789,311	S	*	6/2017	Okada	D13/182
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D835,804	S	*	12/2018	Ito	D24/225
D836,211	S	*	12/2018	Ito	D24/225
D843,011	S	*	3/2019	Ito	D24/225
D843,012	S	*	3/2019	Ito	D24/225
D843,013	S	*	3/2019	Ito	D24/225
D843,594	S	*	3/2019	Ito	D24/225
D855,205	S	*	7/2019	Ito	D24/225
D855,208	S	*	7/2019	Ito	D24/225
D855,210	S	*	7/2019	Ito	D24/225

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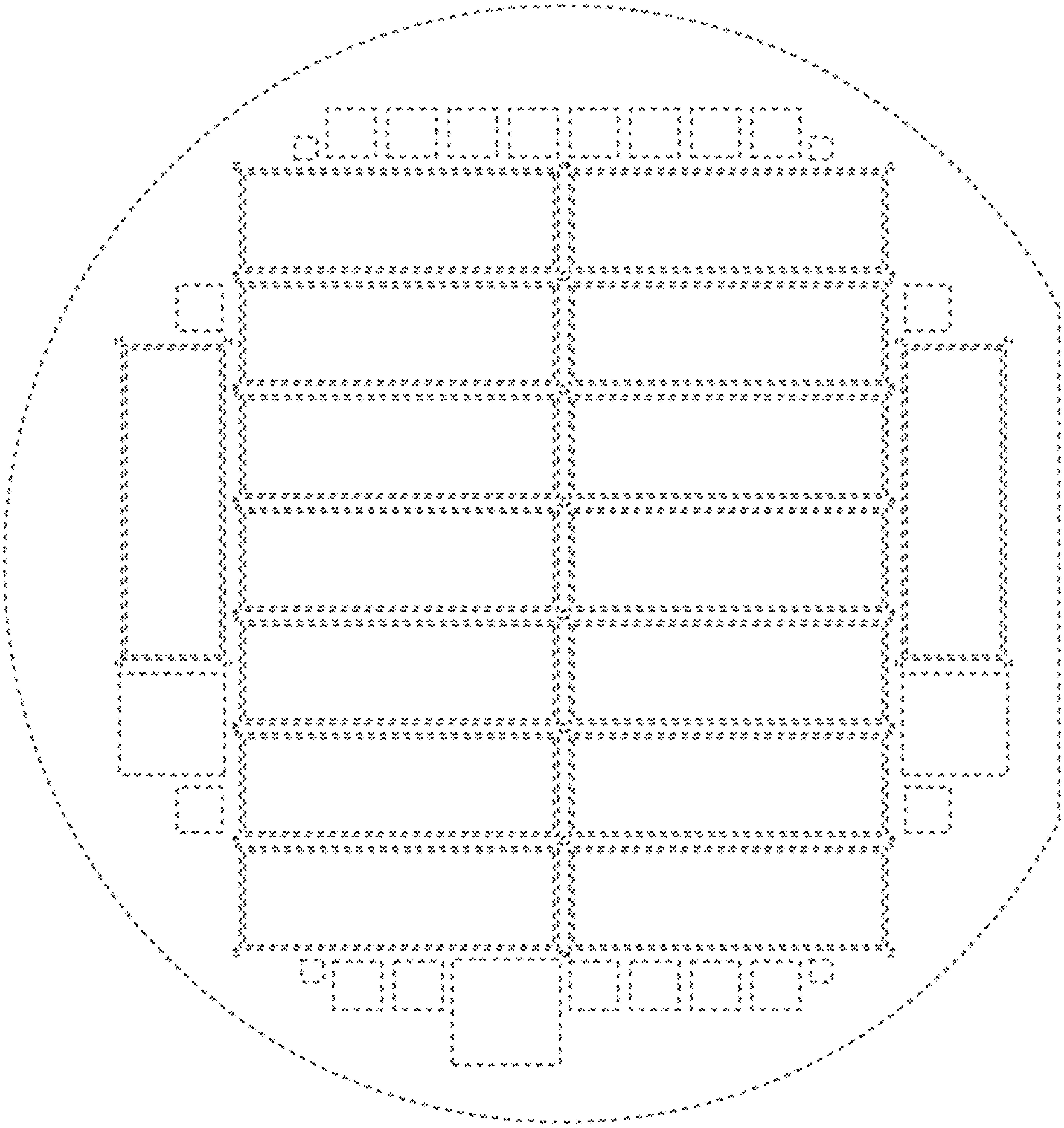

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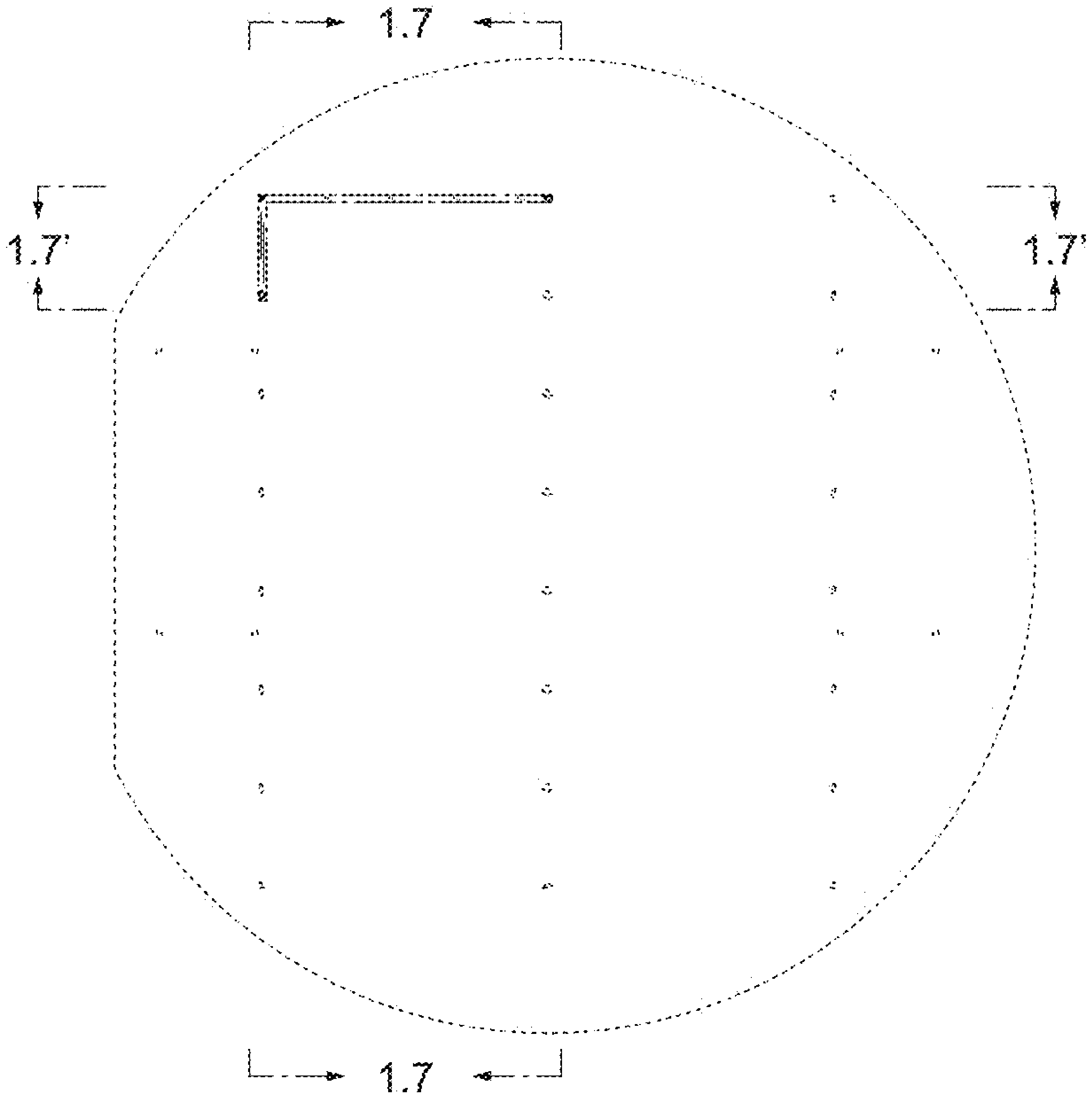

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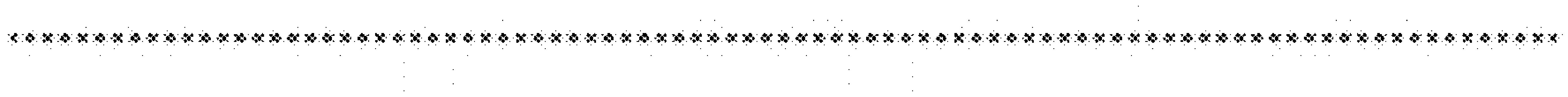

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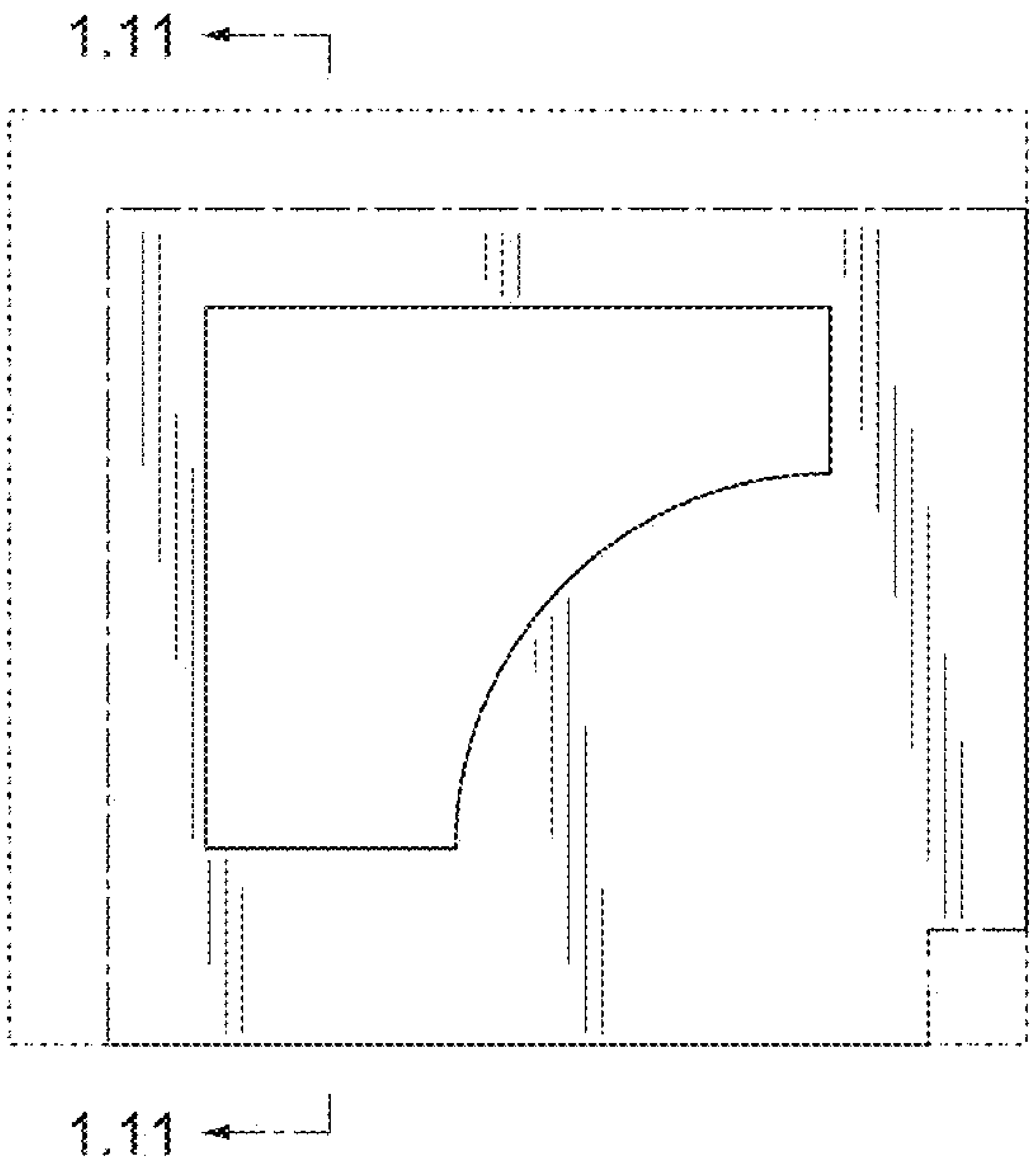
【1.7】

【1.8】



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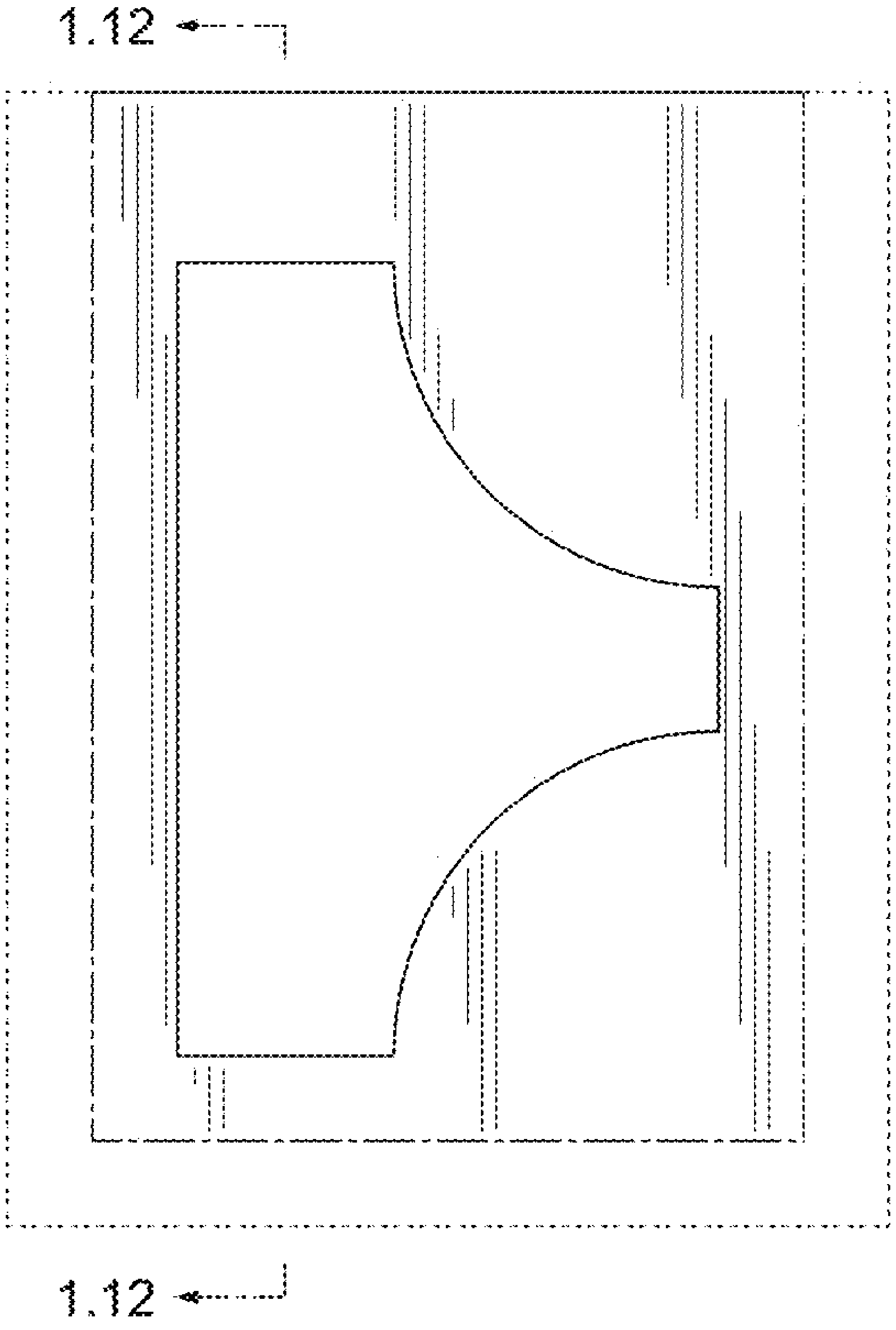

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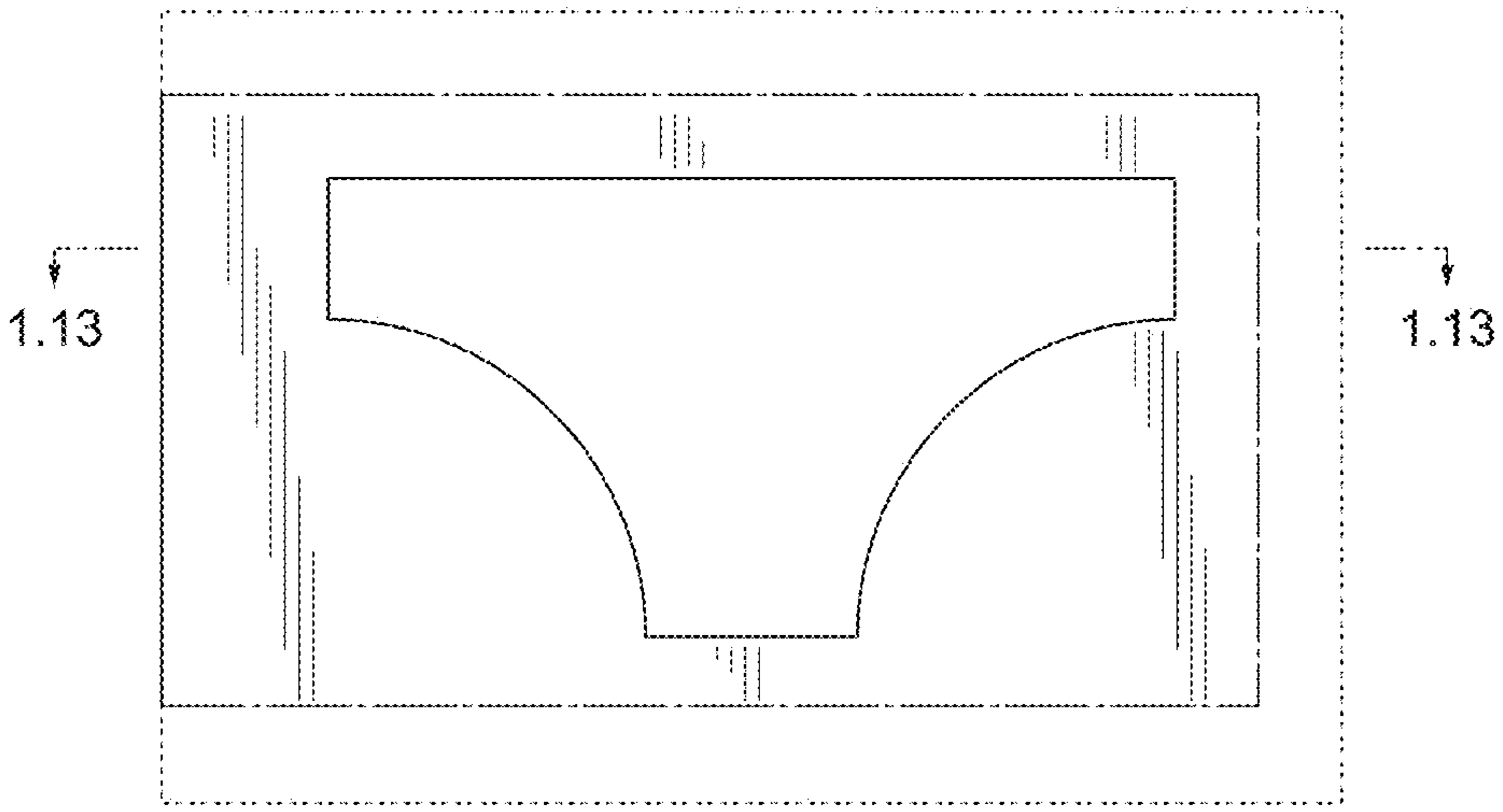

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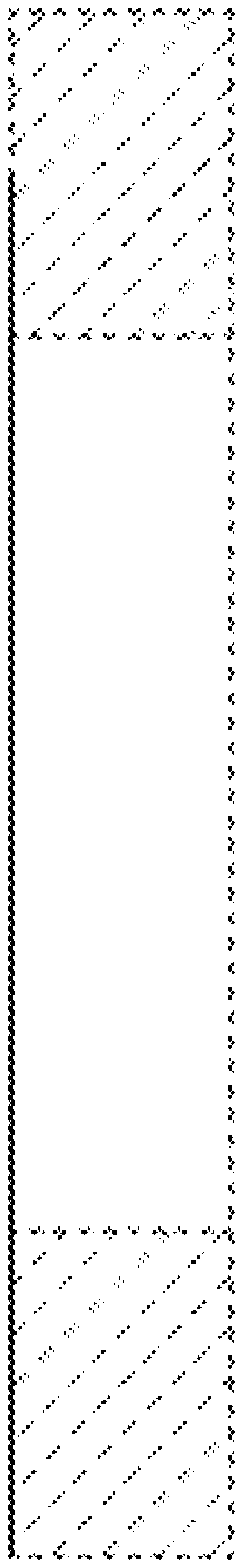

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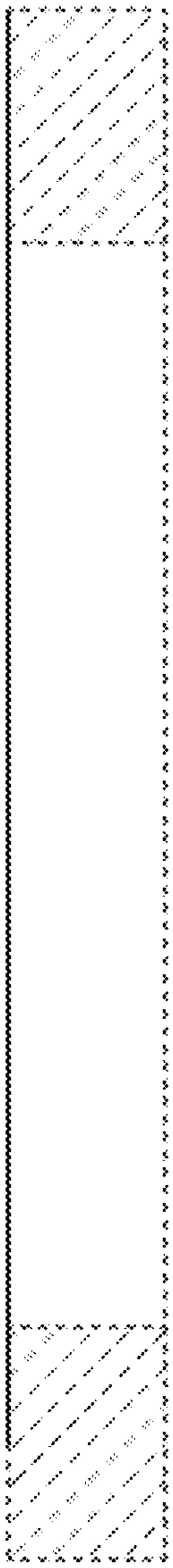

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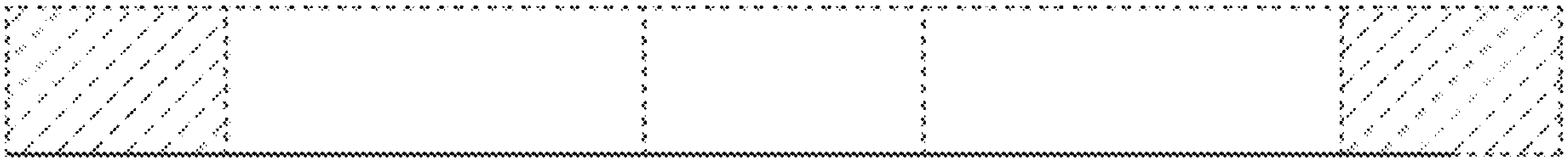

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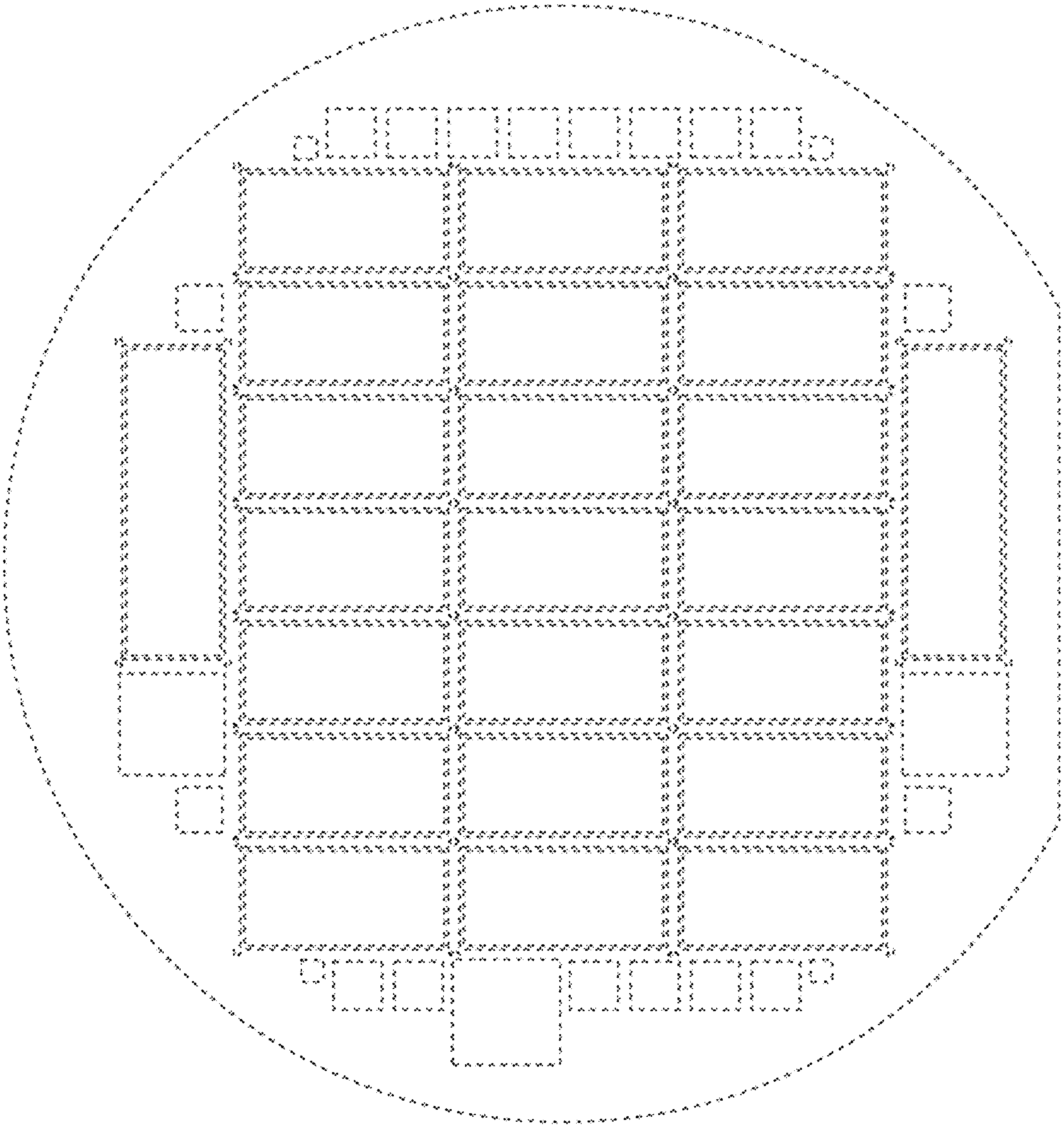

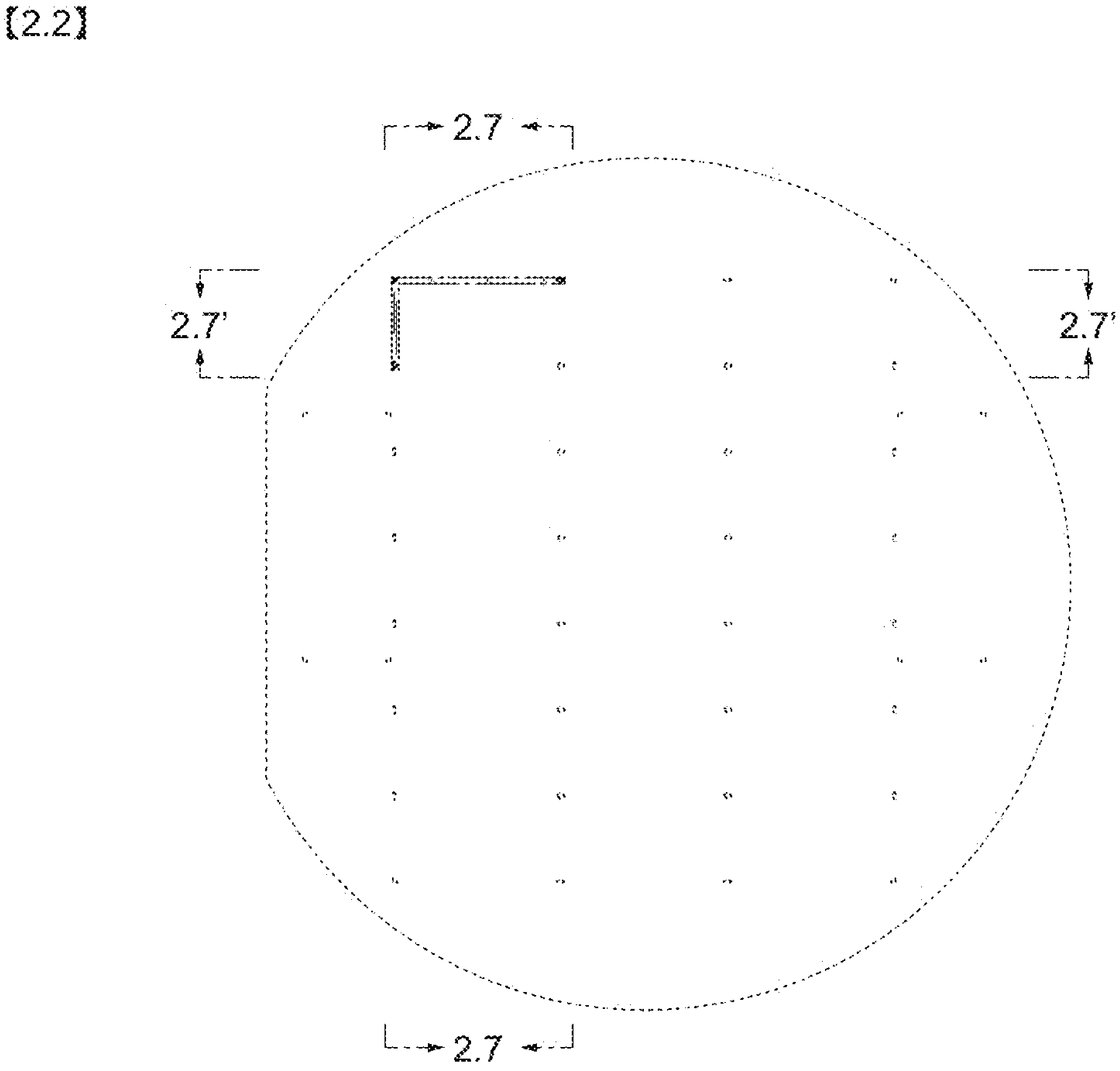
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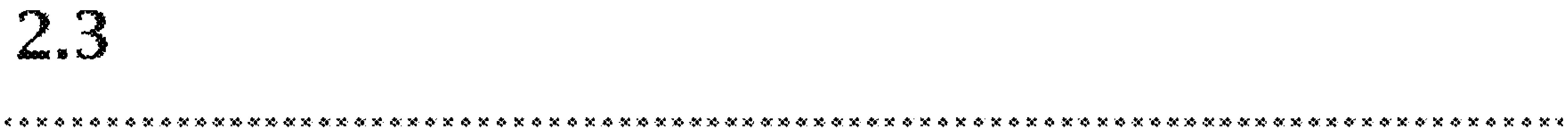
2.7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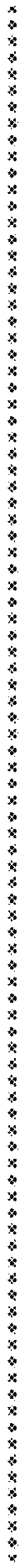

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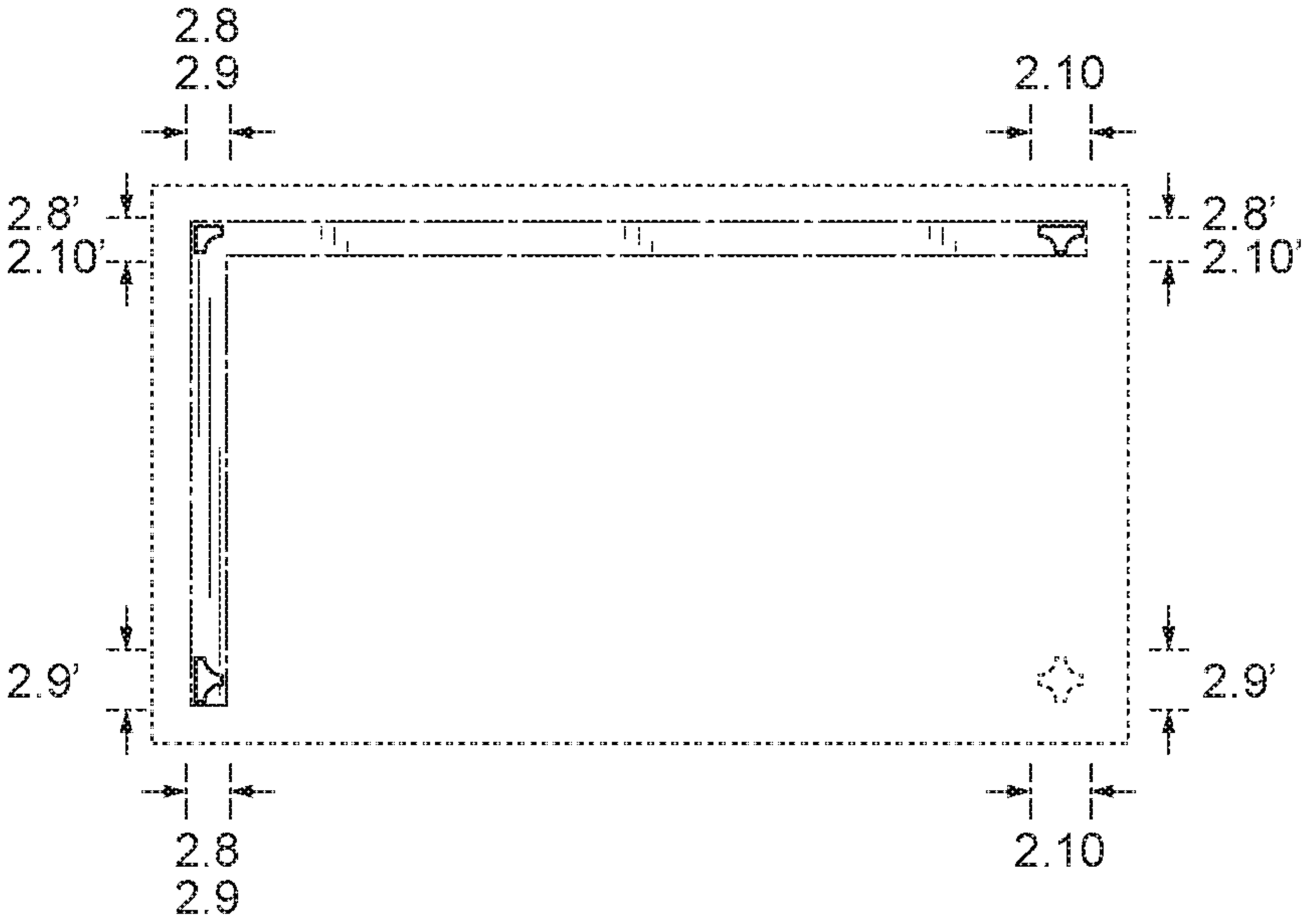

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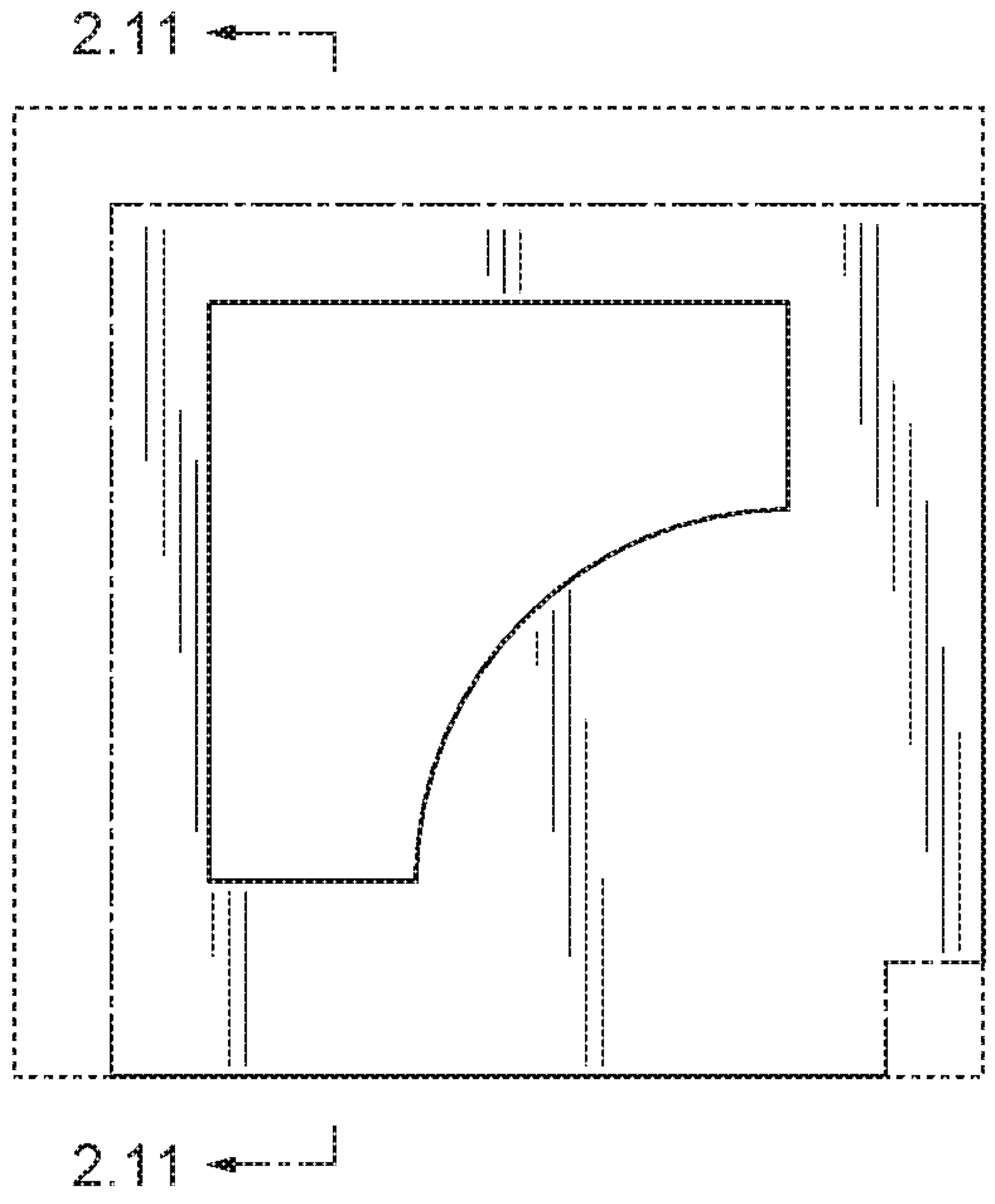

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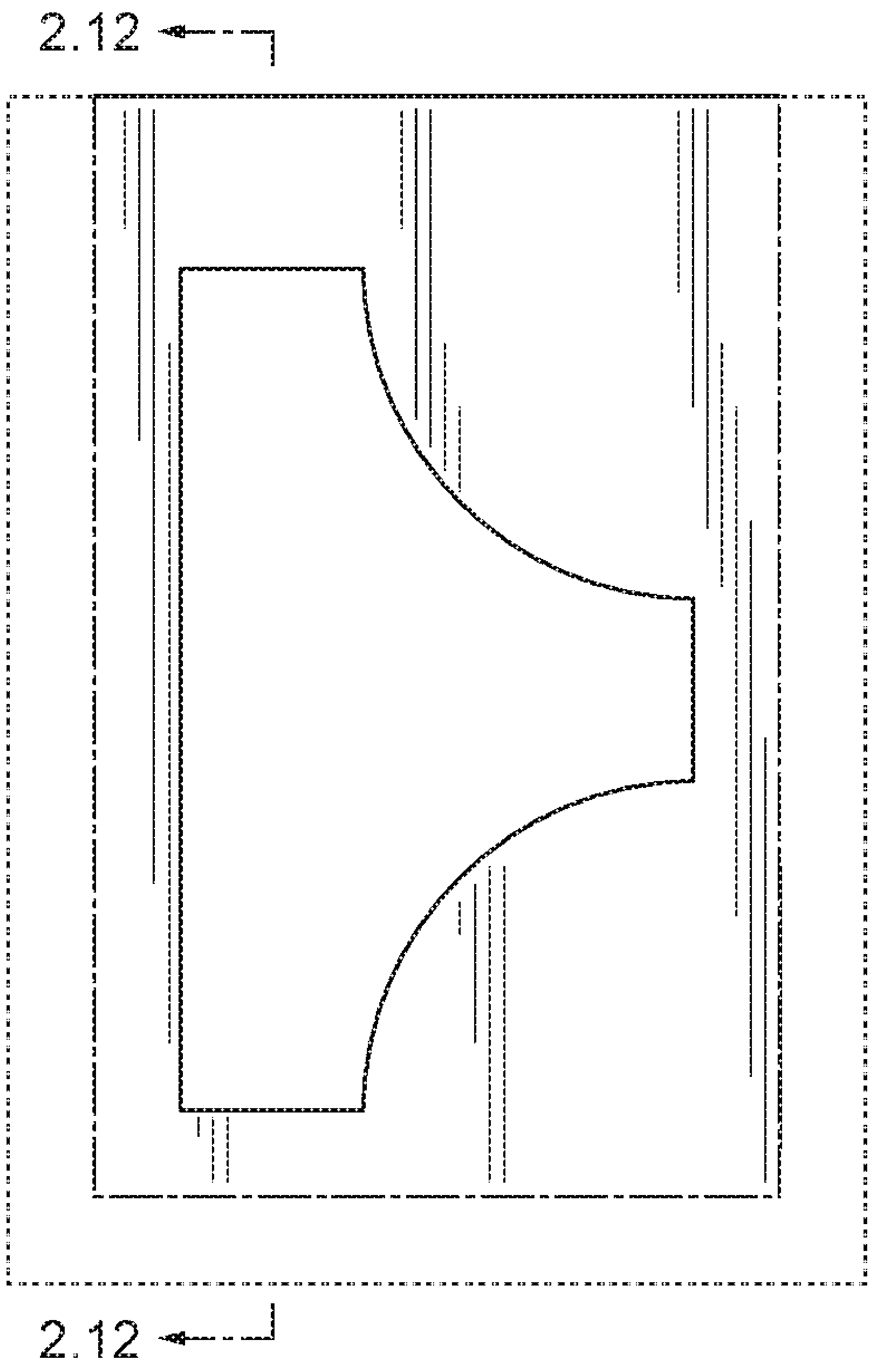

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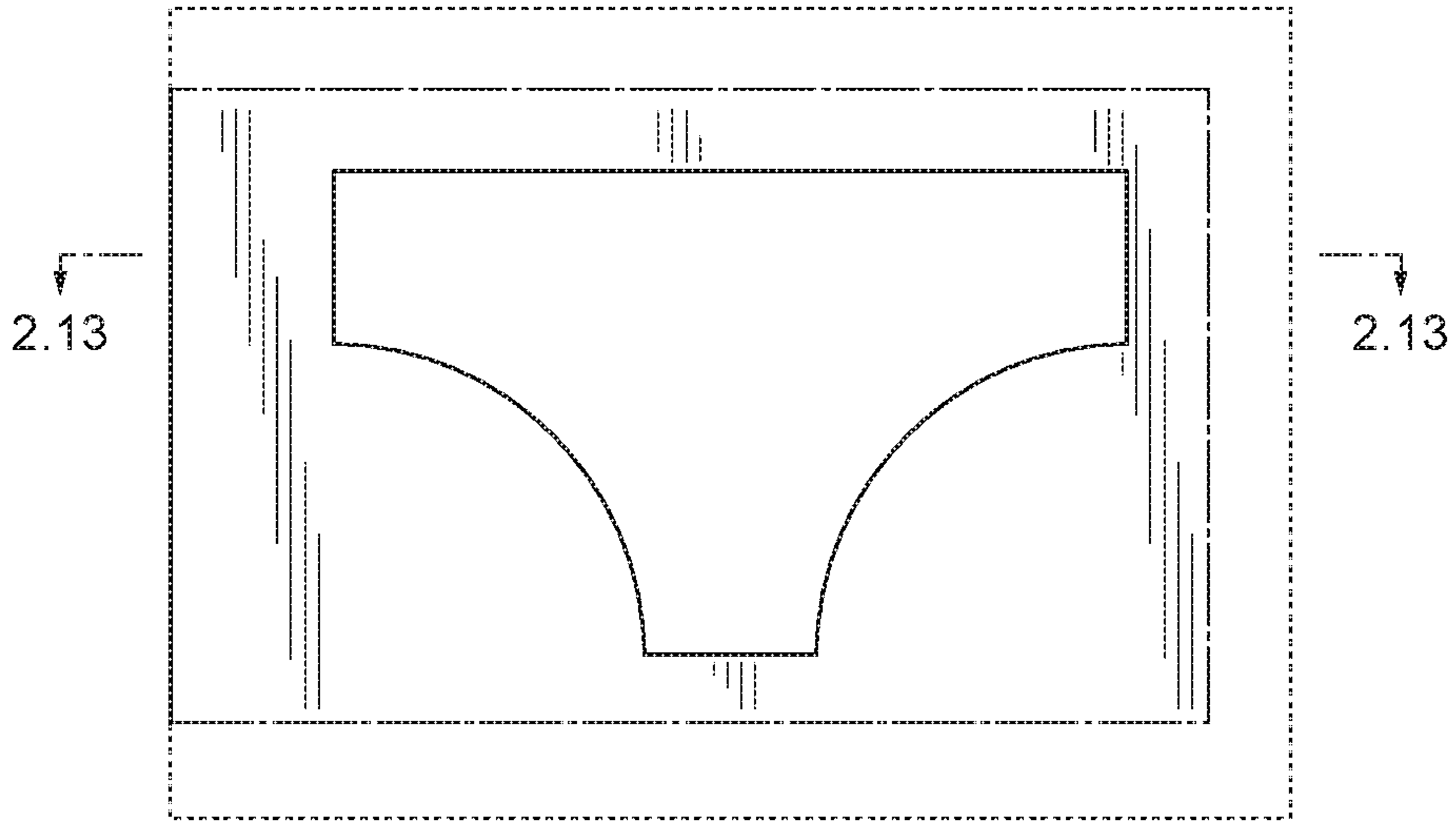

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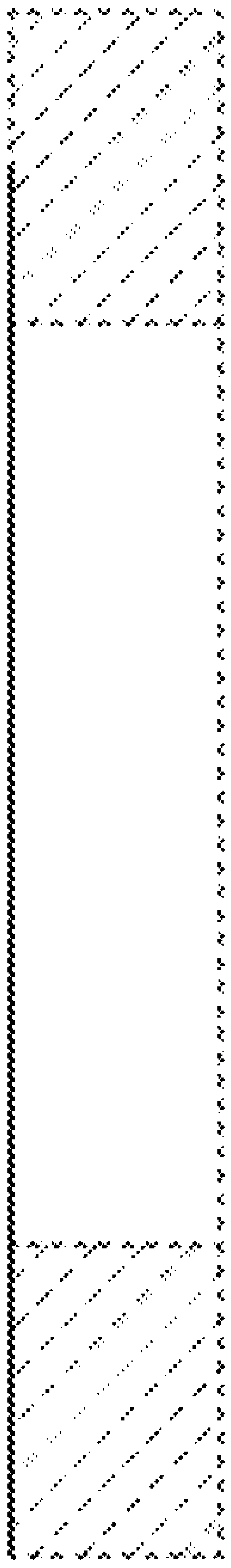

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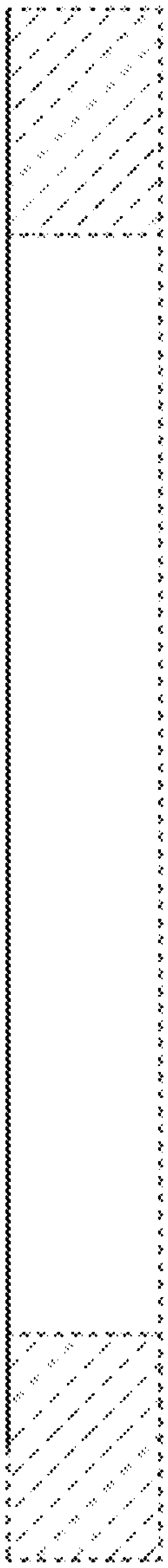

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